

# 8-Mbit (512 K × 16) Static RAM

## Features

- Very high speed: 55 ns
- Wide voltage range: 1.65 V–2.25 V
- Pin compatible with CY62157DV18 and CY62157DV20
- Ultra low standby power
  - Typical Standby current: 2  $\mu$ A
  - Maximum Standby current: 8  $\mu$ A
- Ultra low active power
  - Typical active current: 1.8 mA at  $f = 1$  MHz
- Easy memory expansion with  $\overline{CE}_1$ ,  $CE_2$  and  $\overline{OE}$  features
- Automatic power down when deselected
- Complementary metal oxide semiconductor (CMOS) for optimum speed and power
- Available in Pb-free 48-ball very fine-pitch ball grid array (VFBGA) package

## Functional Description

The CY62157EV18 is a high performance CMOS static RAM organized as 512K words by 16 bits. This device features advanced circuit design to provide ultra low active current. This is ideal for providing More Battery Life™ (MoBL®) in portable applications such as cellular telephones. The device also has an automatic power down feature that significantly reduces power

consumption when addresses are not toggling. The device can also be put into standby mode when deselected ( $\overline{CE}_1$  HIGH or  $CE_2$  LOW or both BHE and BLE are HIGH). The input and output pins (I/O<sub>0</sub> through I/O<sub>15</sub>) are placed in a high impedance state when:

- Deselected ( $\overline{CE}_1$  HIGH or  $CE_2$  LOW)
- Outputs are disabled ( $\overline{OE}$  HIGH)
- Both Byte High Enable and Byte Low Enable are disabled ( $\overline{BHE}$ , BLE HIGH) or
- Write operation is active ( $\overline{CE}_1$  LOW,  $CE_2$  HIGH and  $\overline{WE}$  LOW).

Write to the device by taking Chip Enables ( $\overline{CE}_1$  LOW and  $CE_2$  HIGH) and Write Enable ( $\overline{WE}$ ) input LOW. If Byte Low Enable ( $\overline{BLE}$ ) is LOW, then data from I/O pins (I/O<sub>0</sub> through I/O<sub>7</sub>), is written into the location specified on the address pins (A<sub>0</sub> through A<sub>18</sub>). If Byte High Enable ( $\overline{BHE}$ ) is LOW, then data from I/O pins (I/O<sub>8</sub> through I/O<sub>15</sub>) is written into the location specified on the address pins (A<sub>0</sub> through A<sub>18</sub>).

Read from the device by taking Chip Enables ( $\overline{CE}_1$  LOW and  $CE_2$  HIGH) and Output Enable ( $\overline{OE}$ ) LOW while forcing the Write Enable ( $\overline{WE}$ ) HIGH. If Byte Low Enable ( $\overline{BLE}$ ) is LOW, then data from the memory location specified by the address pins appear on I/O<sub>0</sub> to I/O<sub>7</sub>. If Byte High Enable ( $\overline{BHE}$ ) is LOW, then data from memory appears on I/O<sub>8</sub> to I/O<sub>15</sub>. See the [Truth Table on page 13](#) for a complete description of read and write modes.

For a complete list of related documentation, [click here](#).

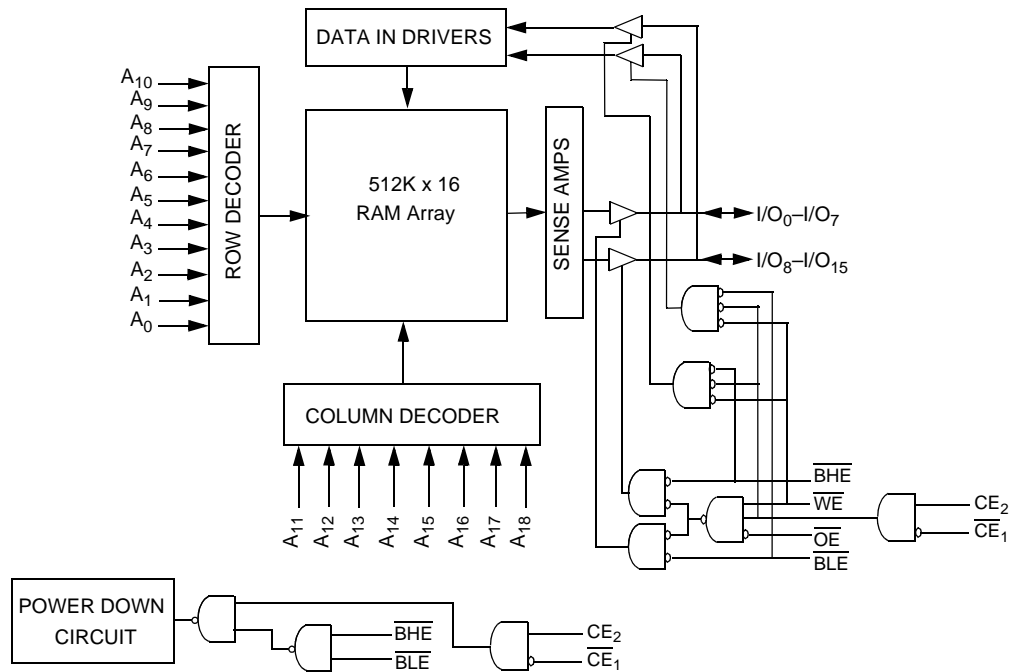
## Product Portfolio

Product	V <sub>CC</sub> Range (V)			Speed (ns)	Power Dissipation					
					Operating I <sub>CC</sub> , (mA)				Standby, I <sub>SB2</sub> (μA)	
	f = 1MHz		f = f <sub>max</sub>							
	Min	Typ <sup>[1]</sup>	Max		Typ <sup>[1]</sup>	Max	Typ <sup>[1]</sup>	Max	Typ <sup>[1]</sup>	Max
CY62157EV18	1.65	1.8	2.25	55	1.8	3	18	25	2	8

### Note

1. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at  $V_{CC} = V_{CC(typ)}$ ,  $T_A = 25$  °C.

## Logic Block Diagram

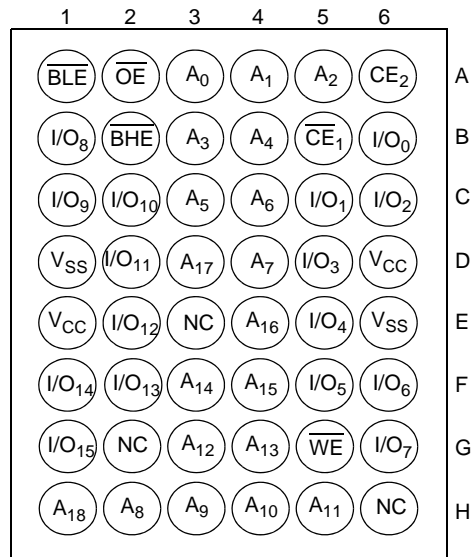


## Contents

<b>Pin Configuration .....</b>	<b>4</b>	<b>Package Diagram .....</b>	<b>15</b>
<b>Maximum Ratings .....</b>	<b>5</b>	<b>Acronyms .....</b>	<b>16</b>
<b>Operating Range .....</b>	<b>5</b>	<b>Document Conventions .....</b>	<b>16</b>
<b>Electrical Characteristics .....</b>	<b>5</b>	Units of Measure .....	16
<b>Capacitance .....</b>	<b>6</b>	<b>Document History .....</b>	<b>17</b>
<b>Thermal Resistance .....</b>	<b>6</b>	<b>Sales, Solutions, and Legal Information .....</b>	<b>19</b>
<b>AC Test Loads and Waveforms .....</b>	<b>6</b>	Worldwide Sales and Design Support .....	19
<b>Data Retention Characteristics .....</b>	<b>7</b>	Products .....	19
<b>Data Retention Waveform .....</b>	<b>7</b>	PSoC® Solutions .....	19
<b>Switching Characteristics .....</b>	<b>8</b>	Cypress Developer Community .....	19
<b>Switching Waveforms .....</b>	<b>9</b>	Technical Support .....	19
<b>Truth Table .....</b>	<b>13</b>		
<b>Ordering Information .....</b>	<b>14</b>		
Ordering Code Definitions .....	14		

## Pin Configuration

**Figure 1. 48-ball VFBGA pinout (Top View) [2]**



**Note**

2. NC pins are not connected on the die.

## Maximum Ratings

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Storage temperature ..... -65 °C to + 150 °C

Ambient temperature with power applied ..... -55 °C to + 125 °C

Supply voltage to ground potential ..... -0.2 V to 2.45 V ( $V_{CCmax} + 0.2$  V)

DC voltage applied to outputs in High-Z state <sup>[3, 4]</sup> ..... -0.2 V to 2.45 V ( $V_{CCmax} + 0.2$  V)

DC input voltage <sup>[3, 4]</sup> ..... -0.2 V to 2.45 V ( $V_{CCmax} + 0.2$  V)

Output current into outputs (LOW) ..... 20 mA

Static discharge voltage (in accordance with MIL-STD-883, Method 3015) ..... > 2001 V

Latch-up current ..... > 200 mA

## Operating Range

Device	Range	Ambient Temperature	$V_{CC}$ <sup>[5]</sup>
CY62157EV18LL	Industrial	-40 °C to +85 °C	1.65 V to 2.25 V

## Electrical Characteristics

Over the Operating Range

Parameter	Description	Test Conditions	55 ns			Unit
			Min	Typ <sup>[6]</sup>	Max	
$V_{OH}$	Output HIGH voltage	$I_{OH} = -0.1$ mA, $V_{CC} = 1.65$ V	1.4	—	—	V
$V_{OL}$	Output LOW voltage	$I_{OL} = 0.1$ mA, $V_{CC} = 1.65$ V	—	—	0.2	V
$V_{IH}$	Input HIGH voltage	$V_{CC} = 1.65$ V to 2.25 V	1.4	—	$V_{CC} + 0.2$ V	V
$V_{IL}$	Input LOW voltage	$V_{CC} = 1.65$ V to 2.25 V	-0.2	—	0.4	V
$I_{IX}$	Input leakage current	$GND \leq V_I \leq V_{CC}$	-1	—	+1	μA
$I_{OZ}$	Output leakage current	$GND \leq V_O \leq V_{CC}$ , output disabled	-1	—	+1	μA
$I_{CC}$	$V_{CC}$ operating supply current	$f = f_{max} = 1/t_{RC}$ , $V_{CC} = V_{CC(max)}$ , $I_{OUT} = 0$ mA	—	18	25	mA
		$f = 1$ MHz, CMOS levels	—	1.8	3	
$I_{SB1}^{[7]}$	Automatic CE power down current – CMOS inputs	$\overline{CE}_1 \geq V_{CC} - 0.2$ V or $CE_2 \leq 0.2$ V, $V_{IN} \geq V_{CC} - 0.2$ V, $V_{IN} \leq 0.2$ V, $f = f_{max}$ (address and data only), $f = 0$ (OE, WE, BHE and BLE), $V_{CC} = V_{CC(max)}$ .	—	2	8	μA
$I_{SB2}^{[7]}$	Automatic CE power down current – CMOS Inputs	$\overline{CE}_1 \geq V_{CC} - 0.2$ V or $CE_2 \leq 0.2$ V, $V_{IN} \geq V_{CC} - 0.2$ V or $V_{IN} \leq 0.2$ V, $f = 0$ , $V_{CC} = V_{CC(max)}$ .	—	2	8	μA

### Notes

- $V_{IL(min)}$  = -2.0 V for pulse durations less than 20 ns.
- $V_{IH(max)}$  =  $V_{CC} + 0.5$  V for pulse durations less than 20 ns.
- Full Device AC operation assumes a 100 μs ramp time from 0 to  $V_{CC}$  (min) and 200 μs wait time after  $V_{CC}$  stabilization.
- Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at  $V_{CC} = V_{CC(typ)}$ ,  $T_A = 25$  °C.
- Chip enable ( $\overline{CE}$ ) and byte enables ( $\overline{BHE}$  and  $\overline{BLE}$ ) need to be tied to CMOS levels to meet the  $I_{SB1}/I_{SB2}/I_{CCDR}$  spec. Other inputs can be left floating.

## Capacitance

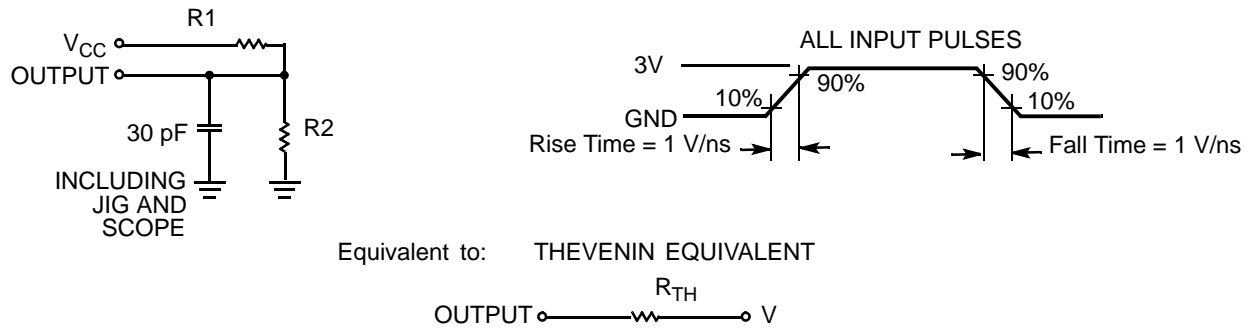
Parameter <sup>[8]</sup>	Description	Test Conditions	Max	Unit
C <sub>IN</sub>	Input capacitance	T <sub>A</sub> = 25 °C, f = 1 MHz, V <sub>CC</sub> = V <sub>CC(typ)</sub>	10	pF
C <sub>OUT</sub>	Output capacitance		10	pF

## Thermal Resistance

Parameter <sup>[8]</sup>	Description	Test Conditions	BGA	Unit
Θ <sub>JA</sub>	Thermal resistance (junction to ambient)	Still air, soldered on a 3 × 4.5 inch, four-layer printed circuit board	48.34	°C/W
Θ <sub>JC</sub>	Thermal resistance (junction to case)		8.78	°C/W

## AC Test Loads and Waveforms

Figure 2. AC Test Loads and Waveforms



Parameters	Value	Unit
R1	13500	Ω
R2	10800	Ω
R <sub>TH</sub>	6000	Ω
V <sub>TH</sub>	0.80	V

### Note

8. Tested initially and after any design or process changes that may affect these parameters.

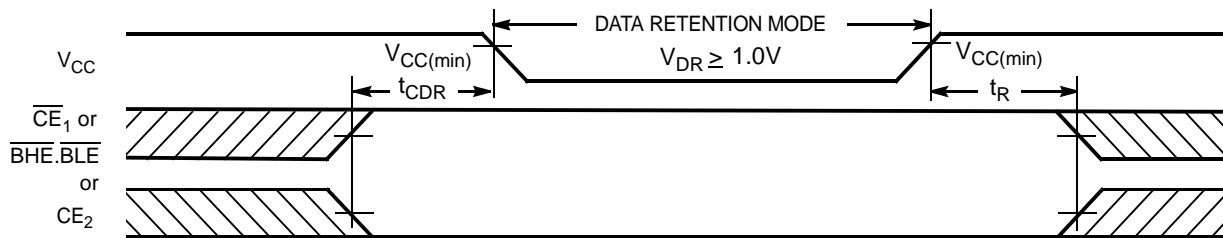
## Data Retention Characteristics

Over the Operating Range

Parameter	Description	Conditions	Min	Typ <sup>[9]</sup>	Max	Unit
$V_{DR}$	$V_{CC}$ for data retention		1.0	–	–	V
$I_{CCDR}$ <sup>[10]</sup>	Data retention current	$V_{CC} = V_{DR}$ , $\overline{CE}_1 \geq V_{CC} - 0.2\text{ V}$ , $CE_2 \leq 0.2\text{ V}$ , $V_{IN} \geq V_{CC} - 0.2\text{ V}$ or $V_{IN} \leq 0.2\text{ V}$	–	1	3	$\mu\text{A}$
$t_{CDR}$ <sup>[11]</sup>	Chip deselect to data retention time		0	–	–	ns
$t_R$ <sup>[12]</sup>	Operation recovery time		55	–	–	ns

## Data Retention Waveform

Figure 3. Data Retention Waveform<sup>[13]</sup>



### Notes

- Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at  $V_{CC} = V_{CC(typ)}$ ,  $T_A = 25^\circ\text{C}$ .
- Chip enable ( $\overline{CE}$ ) and byte enables ( $\overline{BHE}$  and  $\overline{BLE}$ ) need to be tied to CMOS levels to meet the  $I_{SB1}/I_{SB2}/I_{CCDR}$  spec. Other inputs can be left floating.
- Tested initially and after any design or process changes that may affect these parameters.
- Full device operation requires linear  $V_{CC}$  ramp from  $V_{DR}$  to  $V_{CC(min)} \geq 100\ \mu\text{s}$  or stable at  $V_{CC(min)} \geq 100\ \mu\text{s}$ .
- $\overline{BHE.BLE}$  is the AND of both  $\overline{BHE}$  and  $\overline{BLE}$ . Deselect the chip by either disabling chip enable signals or by disabling both  $\overline{BHE}$  and  $\overline{BLE}$ .

## Switching Characteristics

Over the Operating Range

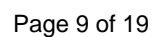
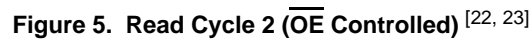
Parameter <sup>[14, 15]</sup>	Description	55 ns		Unit
		Min	Max	
Read Cycle				
t <sub>RC</sub>	Read cycle time	55	–	ns
t <sub>AA</sub>	Address to data valid	–	55	ns
t <sub>OHA</sub>	Data hold from address change	10	–	ns
t <sub>ACE</sub>	$\overline{CE}_1$ LOW and CE <sub>2</sub> HIGH to data valid	–	55	ns
t <sub>DOE</sub>	$\overline{OE}$ LOW to data valid	–	25	ns
t <sub>LZOE</sub>	$\overline{OE}$ LOW to Low-Z <sup>[16]</sup>	5	–	ns
t <sub>HZOE</sub>	$\overline{OE}$ HIGH to High-Z <sup>[16, 17]</sup>	–	18	ns
t <sub>LZCE</sub>	$\overline{CE}_1$ LOW and CE <sub>2</sub> HIGH to Low-Z <sup>[16]</sup>	10	–	ns
t <sub>HZCE</sub>	$\overline{CE}_1$ HIGH and CE <sub>2</sub> LOW to High-Z <sup>[16, 17]</sup>	–	18	ns
t <sub>PU</sub>	$\overline{CE}_1$ LOW and CE <sub>2</sub> HIGH to power up	0	–	ns
t <sub>PD</sub>	$\overline{CE}_1$ HIGH and CE <sub>2</sub> LOW to power down	–	55	ns
t <sub>DBE</sub>	$\overline{BLE}/\overline{BHE}$ LOW to data valid	–	55	ns
t <sub>LZBE</sub> <sup>[18]</sup>	$\overline{BLE}/\overline{BHE}$ LOW to Low-Z <sup>[16]</sup>	10	–	ns
t <sub>HZBE</sub>	$\overline{BLE}/\overline{BHE}$ HIGH to High-Z <sup>[16, 17]</sup>	–	18	ns
Write Cycle <sup>[19, 20]</sup>				
t <sub>WC</sub>	Write cycle time	45	–	ns
t <sub>SCE</sub>	$\overline{CE}_1$ LOW and CE <sub>2</sub> HIGH to write end	35	–	ns
t <sub>AW</sub>	Address setup to write end	35	–	ns
t <sub>HA</sub>	Address hold from write end	0	–	ns
t <sub>SA</sub>	Address setup to write start	0	–	ns
t <sub>PWE</sub>	$\overline{WE}$ pulse width	35	–	ns
t <sub>BW</sub>	$\overline{BLE}/\overline{BHE}$ LOW to write end	35	–	ns
t <sub>SD</sub>	Data setup to write end	25	–	ns
t <sub>HD</sub>	Data hold from write end	0	–	ns
t <sub>HZWE</sub>	$\overline{WE}$ LOW to High-Z <sup>[16, 17]</sup>	–	18	ns
t <sub>LZWE</sub>	$\overline{WE}$ HIGH to Low-Z <sup>[16]</sup>	10	–	ns

### Notes

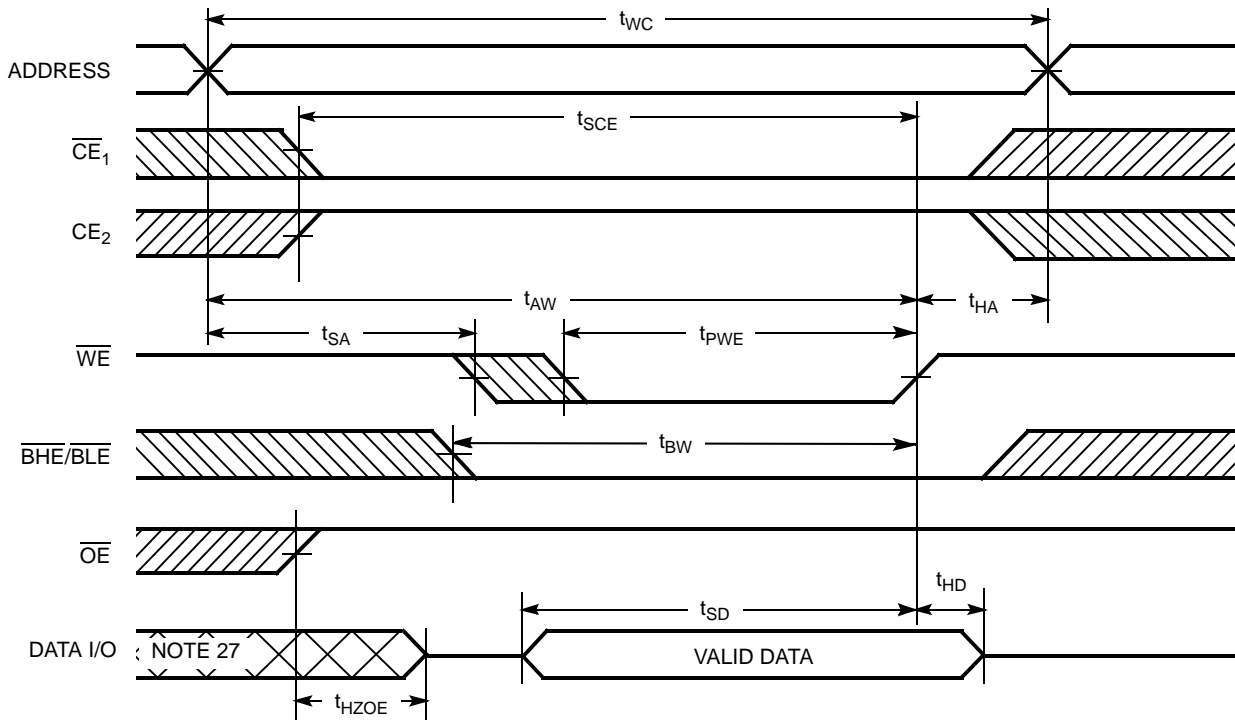
14. Test conditions for all parameters other than tri-state parameters assume signal transition time of 1V/ns or less, timing reference levels of  $V_{CC(typ)}/2$ , input pulse levels of 0 to  $V_{CC(typ)}$ , and output loading of the specified  $I_{OL}/I_{OH}$  as shown in the [Figure 2 on page 6](#).
15. In an earlier revision of this device, under a specific application condition, READ and WRITE operations were limited to switching of the byte enable and/or chip enable signals as described in the Application Notes [AN13842](#) and [AN66311](#). However, the issue has been fixed and in production now, and hence, these Application Notes are no longer applicable. They are available for download on our website as they contain information on the date code of the parts, beyond which the fix has been in production.
16. At any given temperature and voltage condition,  $t_{HZCE}$  is less than  $t_{LZCE}$ ,  $t_{HZBE}$  is less than  $t_{LZBE}$ ,  $t_{HZOE}$  is less than  $t_{LZOE}$ , and  $t_{HZWE}$  is less than  $t_{LZWE}$  for any given device.
17.  $t_{HZOE}$ ,  $t_{HZCE}$ ,  $t_{HZBE}$ , and  $t_{HZWE}$  transitions are measured when the output enters a high impedance state.
18. If both byte enables are toggled together, this value is 10 ns.
19. The internal write time of the memory is defined by the overlap of  $\overline{WE}$ ,  $\overline{CE} = V_{IL}$ ,  $\overline{BHE}$  and/or  $\overline{BLE} = V_{IL}$ , and  $CE_2 = V_{IH}$ . All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input setup and hold timing must be referenced to the edge of the signal that terminates the write.
20. The minimum write cycle time for Write Cycle No. 3 ( $\overline{WE}$  controlled,  $\overline{OE}$  LOW) is the sum of  $t_{HZWE}$  and  $t_{SD}$ .



**Figure 4. Read Cycle 1 (Address Transition Controlled)** <sup>[21, 22]</sup>



**Switching Waveforms** (continued)

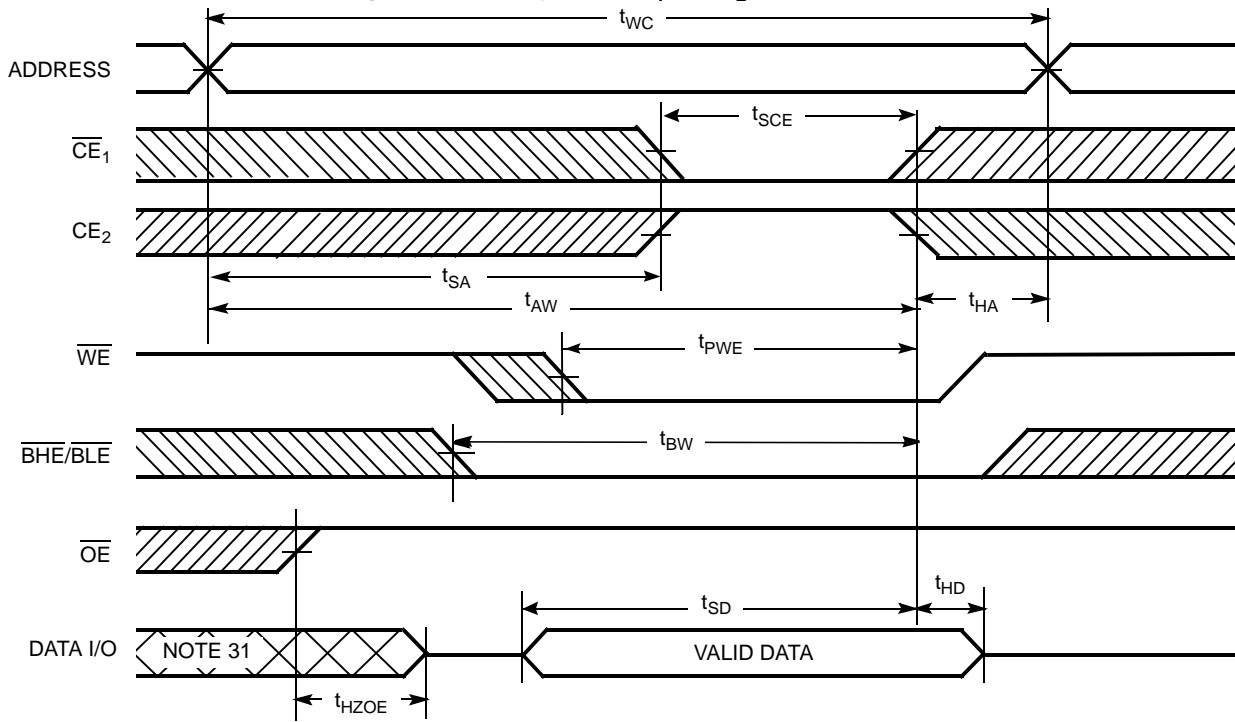
**Figure 6. Write Cycle 1 ( $\overline{WE}$  Controlled)** [24, 25, 26]

**Notes**

24. The internal write time of the memory is defined by the overlap of  $\overline{WE}$ ,  $\overline{CE} = V_{IL}$ ,  $\overline{BHE}$  and/or  $\overline{BLE} = V_{IL}$ , and  $CE_2 = V_{IH}$ . All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input setup and hold timing must be referenced to the edge of the signal that terminates the write.

25. Data I/O is high impedance if  $\overline{OE} = V_{IH}$ .

26. If  $\overline{CE}_1$  goes HIGH and  $CE_2$  goes LOW simultaneously with  $\overline{WE} = V_{IH}$ , the output remains in a high impedance state.

27. During this period, the I/Os are in output state and input signals must not be applied.

**Switching Waveforms (continued)**
**Figure 7. Write Cycle 2 ( $\overline{CE}_1$  or  $CE_2$  Controlled) [28, 29, 30]**

**Notes**

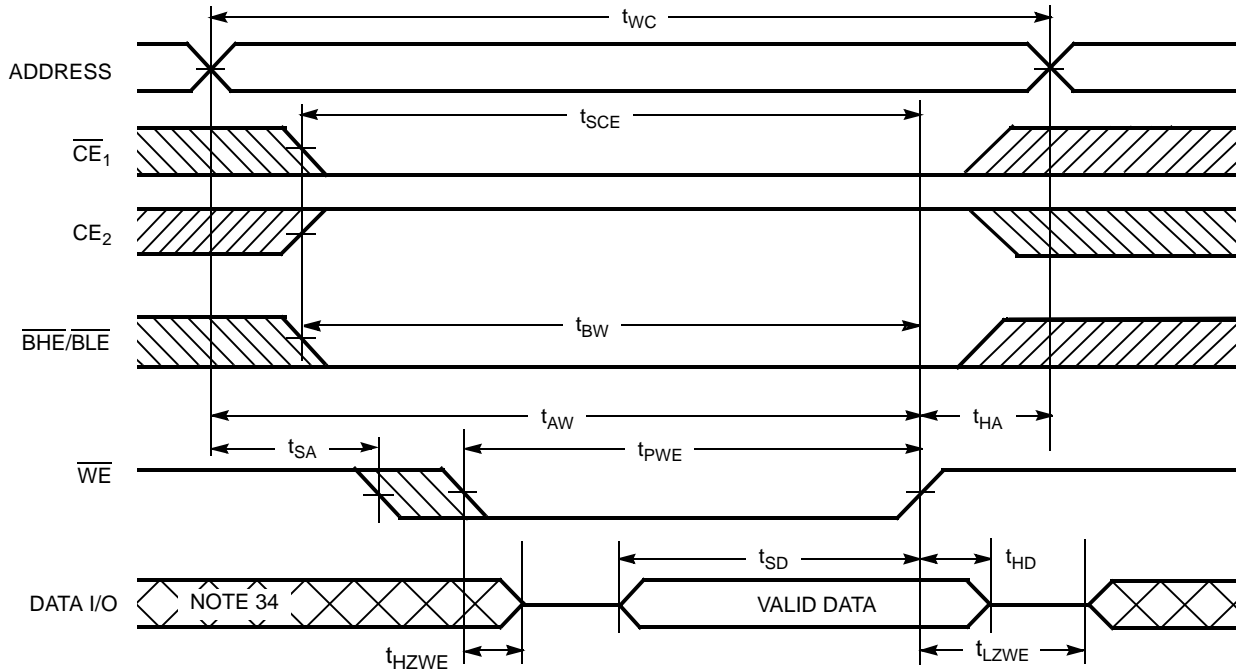
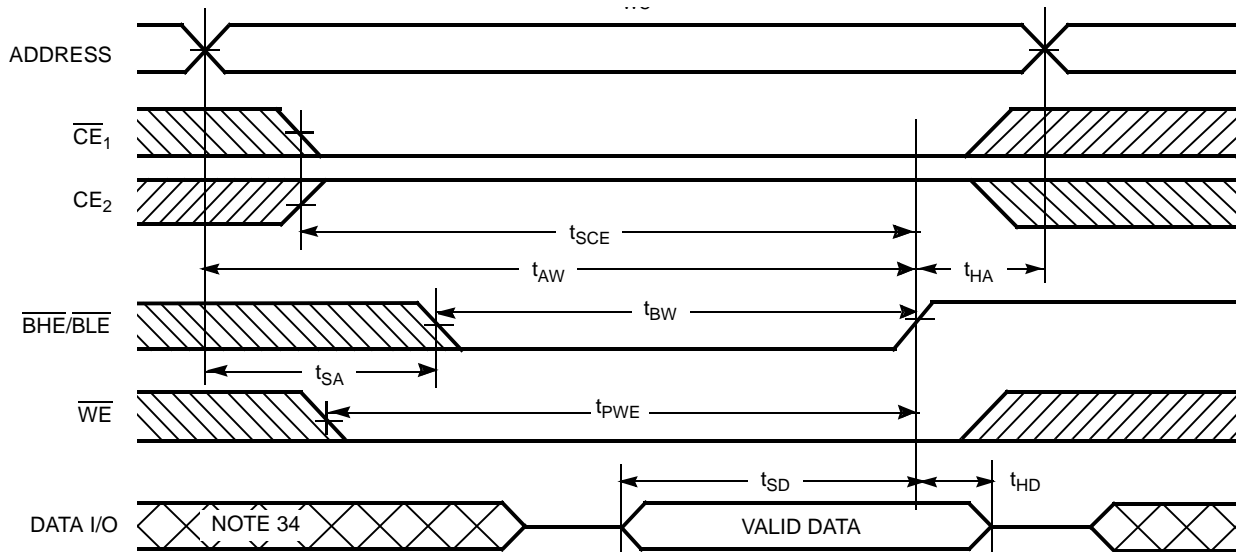
28. The internal write time of the memory is defined by the overlap of  $\overline{WE}$ ,  $\overline{CE} = V_{IL}$ ,  $\overline{BHE}$  and/or  $\overline{BLE} = V_{IL}$ , and  $CE_2 = V_{IH}$ . All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input setup and hold timing must be referenced to the edge of the signal that terminates the write.

29. Data I/O is high impedance if  $\overline{OE} = V_{IH}$ .

30. If  $\overline{CE}_1$  goes HIGH and  $CE_2$  goes LOW simultaneously with  $\overline{WE} = V_{IH}$ , the output remains in a high impedance state.

31. During this period, the I/Os are in output state and input signals must not be applied.

**Switching Waveforms** (continued)

**Figure 8. Write Cycle 3 ( $\overline{\text{WE}}$  Controlled,  $\overline{\text{OE}}$  LOW) [32, 33]**

**Figure 9. Write Cycle 4 ( $\overline{\text{BHE/BLER}}$  Controlled,  $\overline{\text{OE}}$  LOW) [32]**

**Notes**

32. If  $\overline{\text{CE}}_1$  goes HIGH and  $\text{CE}_2$  goes LOW simultaneously with  $\overline{\text{WE}} = V_{IH}$ , the output remains in a high impedance state.

33. The minimum write cycle time for Write Cycle No. 3 ( $\overline{\text{WE}}$  controlled,  $\overline{\text{OE}}$  LOW) is the sum of  $t_{HZWE}$  and  $t_{SD}$ .

34. During this period, the I/Os are in output state and input signals must not be applied.

## Truth Table

$\overline{CE}_1$	$CE_2$	$\overline{WE}$	$\overline{OE}$	$\overline{BHE}$	$\overline{BLE}$	Inputs/Outputs	Mode	Power
H	$X^{[35]}$	X	X	$X^{[35]}$	$X^{[35]}$	High-Z	Deselect/Power down	Standby ( $I_{SB}$ )
$X^{[35]}$	L	X	X	$X^{[35]}$	$X^{[35]}$	High-Z	Deselect/Power down	Standby ( $I_{SB}$ )
$X^{[35]}$	$X^{[35]}$	X	X	H	H	High-Z	Deselect/Power down	Standby ( $I_{SB}$ )
L	H	H	L	L	L	Data out ( $I/O_0$ – $I/O_{15}$ )	Read	Active ( $I_{CC}$ )
L	H	H	L	H	L	Data out ( $I/O_0$ – $I/O_7$ ); High-Z ( $I/O_8$ – $I/O_{15}$ )	Read	Active ( $I_{CC}$ )
L	H	H	L	L	H	High-Z ( $I/O_0$ – $I/O_7$ ); Data out ( $I/O_8$ – $I/O_{15}$ )	Read	Active ( $I_{CC}$ )
L	H	H	H	L	H	High-Z	Output disabled	Active ( $I_{CC}$ )
L	H	H	H	H	L	High-Z	Output disabled	Active ( $I_{CC}$ )
L	H	H	H	L	L	High-Z	Output disabled	Active ( $I_{CC}$ )
L	H	L	X	L	L	Data in ( $I/O_0$ – $I/O_{15}$ )	Write	Active ( $I_{CC}$ )
L	H	L	X	H	L	Data in ( $I/O_0$ – $I/O_7$ ); High-Z ( $I/O_8$ – $I/O_{15}$ )	Write	Active ( $I_{CC}$ )
L	H	L	X	L	H	High-Z ( $I/O_0$ – $I/O_7$ ); Data in ( $I/O_8$ – $I/O_{15}$ )	Write	Active ( $I_{CC}$ )

### Note

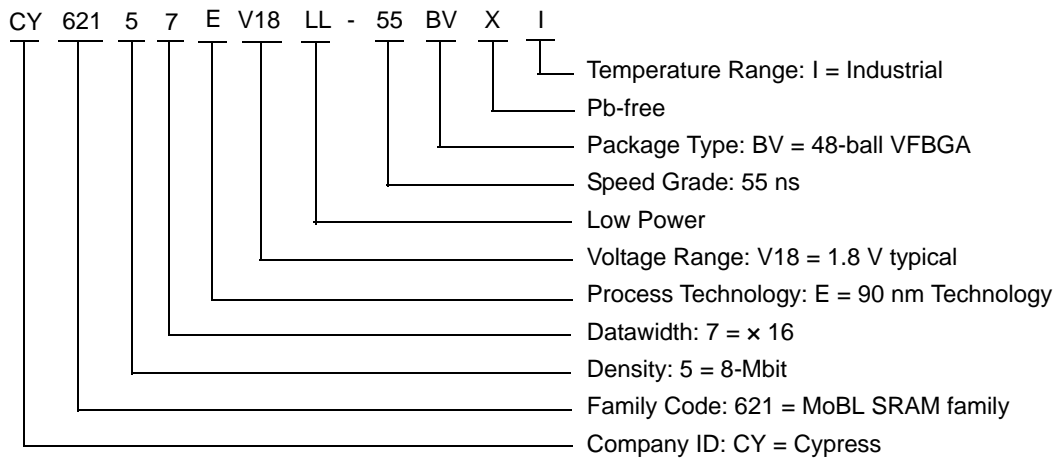
35. The 'X' (Don't care) state for the Chip enables and Byte enables in the truth table refer to the logic state (either HIGH or LOW). Intermediate voltage levels on these pins is not permitted.

## Ordering Information

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
55	CY62157EV18LL-55BVXI	51-85150	48-ball VFBGA (Pb-free)	Industrial

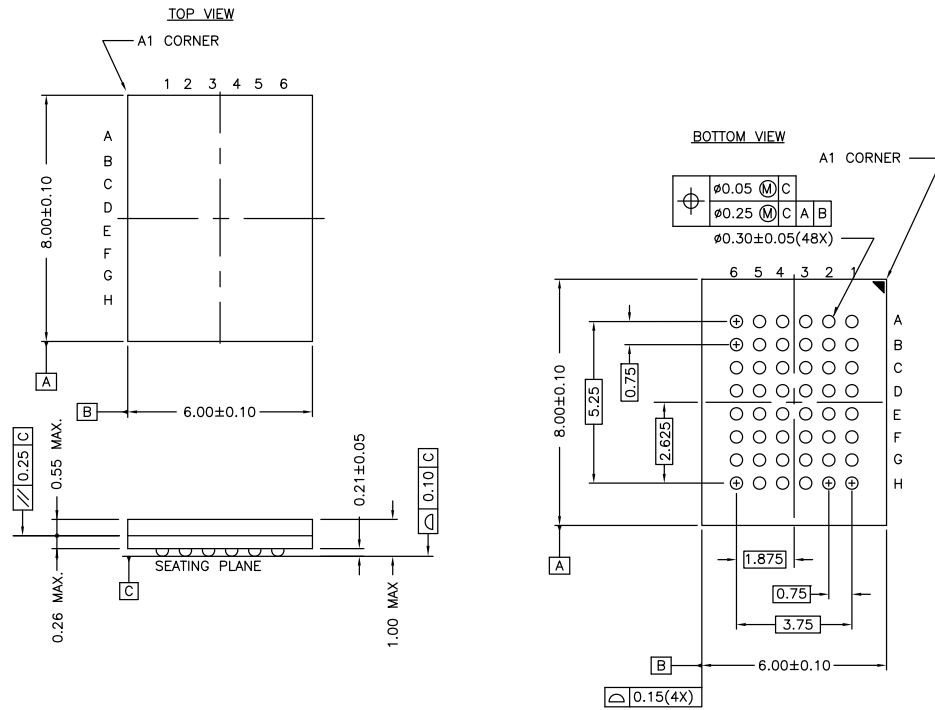
Contact your local Cypress sales representative for availability of these parts.

## Ordering Code Definitions



## Package Diagram

**Figure 10. 48-ball VFBGA (6 × 8 × 1 mm) BV48/BZ48 Package Outline, 51-85150**



NOTE:  
 PACKAGE WEIGHT: See Cypress Package Material Declaration Datasheet (PMDD)  
 posted on the Cypress web.

51-85150 \*H

## Acronyms

Acronym	Description
BHE	Byte High Enable
BLE	Byte Low Enable
CE	Chip Enable
CMOS	Complementary Metal Oxide Semiconductor
I/O	Input/Output
OE	Output Enable
SRAM	Static Random Access Memory
VFBGA	Very Fine-Pitch Ball Grid Array
WE	Write Enable

## Document Conventions

### Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
μA	microampere
mA	milliampere
MHz	megahertz
ns	nanosecond
Ω	ohm
pF	picofarad
V	volt
W	watt



## Document History

Document Title: CY62157EV18 MoBL®, 8-Mbit (512 K × 16) Static RAM Document Number: 38-05490				
Rev.	ECN No.	Issue Date	Orig. of Change	Description of Change
**	202862	See ECN	AJU	New data sheet
*A	291272	See ECN	SYT	Converted from Advance Information to Preliminary Changed $V_{CC}$ Max from 2.20 to 2.25 V Changed $V_{CC}$ stabilization time in footnote #7 from 100 $\mu$ s to 200 $\mu$ s Changed $I_{CCDR}$ from 4 to 4.5 $\mu$ A Changed $t_{OHA}$ from 6 ns to 10 ns for both 35 ns and 45 ns Speed Bins Changed $t_{DOE}$ from 15 and 22 ns to 18 and 22 ns for the 35 and 45 ns Speed Bins respectively Changed $t_{HZOE}$ , $t_{HZBE}$ and $t_{HZWE}$ from 12 and 15 ns to 15 and 18 ns for the 35 and 45 ns Speed Bins respectively Changed $t_{HZCE}$ from 12 and 15 ns to 18 and 22 ns for the 35 and 45 ns Speed Bins respectively Changed $t_{SCE}$ , $t_{AW}$ , and $t_{BW}$ from 25 and 40 ns to 30 and 35 ns for the 35 and 45 ns Speed Bins respectively Changed $t_{SD}$ from 15 and 20 ns to 18 and 22 ns for the 35 and 45 ns Speed Bins respectively Added Pb-Free Package Information
*B	444306	See ECN	NXR	Converted from Preliminary to Final Removed 35 ns speed bin and "L" bin Changed ball E3 from DNU to NC Removed redundant footnote on DNU Modified Maximum Ratings spec for Supply Voltage and DC Input Voltage from 2.4V to 2.45V Changed the $I_{CC}$ Typ value from 16 mA to 18 mA and $I_{CC}$ Max value from 28 mA to 25 mA for test condition $f = f_{ax} = 1/t_{RC}$ Changed the $I_{CC}$ Max value from 2.3 mA to 3 mA for test condition $f = 1$ MHz Changed the $I_{SB1}$ and $I_{SB2}$ Max value from 4.5 $\mu$ A to 8 $\mu$ A and Typ value from 0.9 $\mu$ A to 2 $\mu$ A respectively Updated Thermal Resistance table Changed Test Load Capacitance from 50 pF to 30 pF Added Typ value for $I_{CCDR}$ Changed the $I_{CCDR}$ Max value from 4.5 $\mu$ A to 3 $\mu$ A Corrected $t_R$ in Data Retention Characteristics from 100 $\mu$ s to $t_{RC}$ ns Changed $t_{LZOE}$ from 3 to 5, changed $t_{LZCE}$ from 6 to 10, changed $t_{HZCE}$ from 22 to 18, changed $t_{LZBE}$ from 6 to 5, changed $t_{PWE}$ from 30 to 35, changed $t_{SD}$ from 22 to 25, and changed $t_{LZWE}$ from 6 to 10 Added footnote #13 Updated the ordering Information and replaced the Package Name column with Package Diagram
*C	571786	See ECN	VKN	Replaced 45ns speed bin with 55ns
*D	908120	See ECN	VKN	Added footnote #7 related to $I_{SB2}$ Added footnote #12 related AC timing parameters
*E	2934396	06/03/10	VKN	Added footnote #23 related to chip enable Updated package diagram and template

**Document History** (continued)

Document Title: CY62157EV18 MoBL®, 8-Mbit (512 K × 16) Static RAM Document Number: 38-05490				
Rev.	ECN No.	Issue Date	Orig. of Change	Description of Change
*F	3110053	12/14/2010	PRAS	Changed Table Footnotes to Footnotes. Added Ordering Code Definitions.
*G	3243545	04/28/2011	RAME	Updated as per template. Added Acronyms and Units of Measure table.
*H	3295175	06/29/2011	RAME	Added I <sub>SB1</sub> and I <sub>CCDR</sub> to footnotes 7 and 11. Modified footnote 29 and referenced in <a href="#">Truth Table</a> .
*I	4102022	08/22/2013	VINI	Updated <a href="#">Switching Characteristics</a> : Updated Note 15. Updated <a href="#">Package Diagram</a> : spec 51-85150 – Updated to the latest revision *H. Updated in new template.
*J	4384935	05/20/2014	MEMJ	Updated <a href="#">Switching Characteristics</a> : Added Note 20 and referred the same note in “Write Cycle”. Updated <a href="#">Switching Waveforms</a> : Added Note 33 and referred the same note in <a href="#">Figure 8</a> . Completing Sunset Review.
*K	4576526	11/21/2014	MEMJ	Added related documentation hyperlink in page 1.
*L	5759379	06/01/2017	VINI	Updated <a href="#">Thermal Resistance</a> values. Updated the template.

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